

## Claims

[c1] What is claimed is:

1.A method of repairing electrode pattern defects comprising:  
performing an inspection process for determine electrode pattern defects; and  
performing a first repairing process for repairing the electrode pattern electrode defects.

[c2] 2.The method of claim 1, wherein the electrode pattern is a sustain electrode pattern of a plasma display panel (PDP).

[c3] 3.The method of claim 2, wherein the sustain electrode is composed of a transparent conductive material or a metal conductive material.

[c4] 4.The method of claim 1, wherein the electrode pattern defects comprise a pit part such as a hole, an incomplete connection, or a broken connection.

[c5] 5.The method of claim 4, wherein the first repairing process is performed via either partially or completely filling the pit part with a conductive paste.

- [c6] 6.The method of claim 5, wherein the conductive paste is selected from a group consisting of silver paste, ITO paste, IZO paste, gold paste, and silver glue.
- [c7] 7.The method of claim 1, wherein the electrode pattern defects comprise salient parts.
- [c8] 8.The method of claim 7,wherein the method further comprises performing a second repairing process, the second repairing process removing the salient part by means of a laser beam.
- [c9] 9.The method of claim 1, wherein the inspection process comprises an optical inspection process or an electrical inspection process.
- [c10] 10.A method of repairing electrode pattern defects of a plasma display panel (PDP) comprising:  
performing an inspection process to determine a first defect and a second defect of the plasma display panel;  
performing a first repairing process for filling the first defect; and  
performing a second repairing process for removing the second defect.
- [c11] 11.The method of claim 10, wherein the electrode pattern is composed of a transparent conductive material or a metal conductive material.

- [c12] 12.The method of claim 10, wherein the first defect is a pit part of the electrode pattern such as a hole, an incomplete connection, or a broken connection.
- [c13] 13.The method of claim 12, wherein the first repairing process fills the pit part of the electrode pattern with a conductive paste.
- [c14] 14.The method of claim 13, wherein the conductive paste is selected from a group consisting of silver paste, ITO paste, IZO paste, gold paste, and silver glue.
- [c15] 15.The method of claim 13, wherein the pit part is completely filled up in the first repairing process.
- [c16] 16.The method of claim 13, wherein the pit part is partially filled up in the first repairing process.
- [c17] 17.The method of claim 10, wherein the second defect is a salient part of the electrode pattern.
- [c18] 18.The method of claim 17, wherein the second repairing process removes the salient part by means of a laser beam.
- [c19] The method of claim 10, wherein the inspection process comprises an optical inspection process or an electrical inspection process, and the electrode pattern comprises

a sustain electrode pattern, a bus electrode pattern, or an address electrode pattern.